

**REMARKS**

Claims 1-21 and 23-29 are pending in this application. By this Amendment, claims 21, 23- 24 and 26-27 are amended and claim 22 is canceled without prejudice to or disclaimer of the subject matter disclosed therein. Reconsideration of the application is respectfully requested.

The courtesies extended to Applicants' representative by Examiners Doan and Cao at the interview held March 10, 2004 are appreciated. The reasons presented at the interview as warranting favorable action are incorporated into the remarks below and constitute Applicants' record of the interview.

The Office Action rejects claims 21 and 28-29 under 35 U.S.C. §102(b) over Makita et al. (U.S. Patent No. 5,936,291) and claims 21-27 and 29 under 35 U.S.C. §103(a) over Tanamoto et al. (U.S. Patent No. 6,208,000) in view of Zhang et al. (U.S. Patent No. 6,635,521). Applicants respectfully traverse these rejections.

In particular, Makita does not disclose or suggest a method of manufacturing a semiconductor device including at least a first step of forming a semiconductor layer and a second step of forming an insulating body, wherein the second step includes at least forming a first insulating film constituting a portion of the insulating film on the semiconductor layer, depositing granular charge trapping bodies on the first insulating film and forming a second insulating film constituting a second portion of the insulating film on the first insulating film while the charge trapping bodies are kept on the first insulating film, and a density of charged trapping bodies per unit area is about 20%, as recited in independent claim 21.

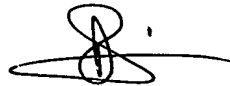
Instead, Makita discloses that a crystalline silicon film is disposed between a first insulating film and a second insulating film, Tanamoto discloses some charge trapping bodies disposed between a first insulating film and a second insulating film, and Zhang discloses forming a transistor with a semiconductor layer on top of a substrate. Thus, Applicants assert

that claims 21-27 and 29 define patentable subject matter. Accordingly, because Makita fails to disclose each and every feature as the claimed invention, and because any combination of the references would not result in the claimed invention, Applicants request that the rejections under 35 U.S.C. §102(b) and §103(a) be withdrawn.

In view of the foregoing, it is respectfully submitted that this application is in condition for allowance. Favorable reconsideration and prompt allowance of claims 21 and 23-29 are earnestly solicited.

Should the Examiner believe that anything further would be desirable in order to place this application in even better condition for allowance, the Examiner is invited to contact the undersigned at the telephone number set forth below.

Respectfully submitted,



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